



# MATERIAL SAFETY DATA SHEET

### 1. PRODUCT & COMPANY IDENTIFICATION

1.1	Product Name :	Gallium Arsenide Phosphide (GsAsP) Chip
	Style/Item No :	GsAsP (HO,HY,SO,HOD TYPE )
1.2	Company Identification :	
	Supplier :	TYNTEK CORPATION
	Name :	Mr. C. K. Perng
	Address :	1378 Ren-Ay Rd.Chunan-Jenn.Miaulih350, Taiwan, R.O.C.
	Telephone:	037-582997
	Facsimile :	037-580866
	e-mail:	187@serv.tyntek.com.tw
1.3	Emergency Contact :	Mr. James Kung
	Telephone:	037-582997
1.4	Manufacturer :	
	Supplier :	TYNTEK CORPATION
	Name :	Mr. C. K. Perng
	Address :	1378 Ren. Ay Rd. Chunan-Jenn. Miaulih350, Taiwan, R.O.C.
	Telephone:	037-582997

#### 2. COMPOSITION/INFORMATION ON INGREDIENTS

Epitaxial layer :	
s than 30%	
n 70%	
8-8(GaP)	
5	

#### **3. HAZARDS IDENTIFICATION**

3.1 MOST IMPORTANT HAZARDS Only those arsenic compounds are considered toxic which Adverse Human Health Effects : may result form thermal decomposition and/or chemical reactions of GaAs, esp.

- -Diarsenic trioxide
- -Arsenic hydride





Poisoning by arsenic compounds can cause irritation of skin and mucous membranes; can damage heart, liver, blood, nerves and metabolism.

Poisoning may result form inhalation and ingestion of dust and mist which occur when handling substance. As result of thermal decomposition arsenic is released. Arsenic can cause cancer in humans.

4. FIRST AID MEASURES					
4.1	Potential routes of exposure	Inhalation, shin, oral, and eye			
4.2	After skin contact	Wash with water and soap.			
4.3	After eye contact	Wash eyes with plenty of water for at least 15minutes.			
4.4	After ingestion	Wash a mouth with plenty of water, and vomit intentionally.			
		Get medical attention.			
4.5	After inhalation	Remove form exposure area to fresh air immediately, get			
		medical attention immediately.			

5.	FIRE FIGHTING MESURES	
5.1	General :	Gallium arsenide Phosphide epitaxial wafer is nonflammable.
		It is subject to decomposition at high temperatures.
		No special extinguishing media needed, adjust
5.2	Appropriate extinguishing media	extinguishing measures to environment.
5.3	Unsuitable extinguishing media	None
	(for safety reasons)	
5.4	Special hazards caused by	Combustion products which are As <sub>2</sub> O <sub>3</sub> ,arsine gas, and arsenic
	substance, combustion products	fumes fumes can be hazardous.
	and emerging gases :	
5.5	Special protection for	Respiratory protection because of As <sub>2</sub> O <sub>3</sub> , arsine, and arsenic
	fire-fighters :	fumes.

### 6. ACCIDENTAL RELEASE MEASURES

6.1 Personal protection : Take precautions during mechanical working and chemical Reactions. Provide good ventilation in manufacturing rooms, exhausts at machines, avoid skin contact.





- 0.2 Environmental protection :
- 6.3 Methods for cleaning up :

Do not pass fine-grained GaAsP epitaxial wafer (suspensions) into Sewerage system (see #13.1)

Wipe with pulp and place in suitable close containers. Sweep up with special vacuum cleaner and place in suitable close containers.

7. HANDLING AND STORAGE					
7.1	Handling, measures for safe	Avoid formation of dust and wear gloves when handling.			
	handling :	(See #6.1)			
7.2	Storage, requirements to storage	Keep dry, close container and store in the roomtemperature			
	rooms, containers and conditions				

<b>8.</b> ]	8. EXPOSURE CONTROL AND PERSONAL PROTECTION							
8.1	Design of technical equipment :	Provide exhausts/covers for equipment and machines where						
		formation of dust a	nd gaseou	is arser	nic com	pounds is to be		
		expected.						
8.2	Occupational exposure limit :	Not available for GaAsP epitaxial wafer.						
		Diarsenic trioxide	Determi	ned as a	arsenic	in total		
		dust.	OSHA	PEL	TWA	$0.01 \text{ mg/m}^3$		
			ACGIH	TLV	TWA	$0.01 \text{ mg/m}^3$		
		Arsine	OSHA	PEL	TWA	0.05 ppm		
			ACGIH	TVL	TWA	0.05 ppm		
		Arsenic	OSHA	PEL	TWA	0.01 mg/m3		
			ACGIH	TLV	TWA	0.01 mg/m3		
8.3	Persnoal protection :							
	Respiratory protection :	Wear Appropriate NI	OSH/MSH	IA appr	oved re	spirator.		
	Hand protection :	Chemical-resistant gloves						
	Eye protection :	Full facemask for dus	sts, vapors					
	Body protection :	Depends on working	place(coat	t, suit, c	overall,	etc.)		
8.4	Further information :	Avoid skin contact, do not eat, smoke, drink during w		during work, do				
		not keep food in wo	orking roo	oms, we	ear appi	appropriate clothing,		
		change soiled clothin	ig, wash ha	ands aft	er work	ζ.		





## 9. PHYSICAL AND CHEMICAL PROPERTIES

9.1	Description :	GaAs	Gap
	Appearance :	Solid substance (wafers)	Solid(wafers)
	Color:	Grey with metallic sheen	Yellow/Orange/Red
	Odor :	None	None
9.2	pН	Not applicable	Not applicable
9.3	Physical and safety data :		
	Melting point/melting area :	1238°C	1465°C
	Boiling point/boiling area :	Not applicable	Not applicable
	Thermal decomposition :	Begin at approx. 300°C slightly	
	Flash point :	Not applicable	Not applicable
	Inflammability :	Not applicable	Not applicable
	Explosive hazard/limits :	Not applicable	Not applicable
	Fire promoting properties :	Not applicable	Not applicable
	Vapor pressure :	Not applicable	Not applicable
	Density:	5.31g/cm3 at 300K	4.13 g/cm3 at 300K
	Solubility :	Not soluble in water	Not soluble in water
9.4	Further information	Forms with moisture in present soluble in water, toxic arsenic laye	ce of atmospheric Oxygen thin, or on the surface.

10. STABILITY AND REACTIVITY					
10.1 Conditions to avoid :	Heating up in air outside closed equipment.				
10.2 Materials to avoid :	Finely divided GaAsP epitaxial wafer can react vigorously				
	steam to prevent release of arsenic fumes or arsine gas.				
10.3 Hazardous decomposition	GaAsP epitaxial wafer when exposed to high temperatures or				
products and reactions :	in contact with strong acids or oxidizers can generate toxic				
	arsenic fumes or arsine gas.				

11. TOXICOLOGICAL INFORMATION				
11.1 Toxicological impact on	l impact on Animal toxicity :			
health:	The data of GaAsP epitaxial wafer is not	available.	The	
	information of GaAs and GaP are as follows			
	GaAs	GaP		
	Intraperitoneal LD30(rat) 10 g/Kg			





	Intraperitoneal LD50(mouse) 4.7 g/Kg
	Oral LD50(mouse)8.0g/kg
	Inorganic arsenic compounds may be dangerous to human
	life(oral from 0.6mg/kg)
After inhalation :	For human beings the threshold of response to arsenic
	Compounds (with regard to As in total dust) is :
	ACGIH TLV TWA 0.01 mg/m <sup>3</sup> .
	May cause inflammation of mucous membranes in Respiratory
	tract.
After ingestion :	Ingestion of arsenic compounds of 50 $\mu$ g/kg/day causes
	Disturbances of digestive tract and kidneys, changes of blood,
	skin irritation etc.
After skin contact :	Arsenic compounds may cause dermatitis of skin.
11.2 Chronic effect :	Arsenic compounds may cause cancer of lungs and skin in
	human beings.
	GaAs was dosed for the hamster in amounts of 0.25mg/time
	×1time/week×15weeks,but lung cancer wasn't admitted.
11.3 Carcinogenicity :	IARC : Human carcinogen(group 1)
	OSHA : Cancer hazard
	NTP: Human carcinogen

12. ECOLOGICAL INFORMATION					
12.1 Degradability and	Not degradable.				
biodegradability:					
12.2 Biological accumulation :	Not available				
12.3 Toxicity to fish :	Not available for GaAsP, LC50 killifish $>$ 10 $\mu$ g/ml(GaAs)				
Diarsenic trioxide :	LC50 goldfish 32 mg/1/7 days				
	LC50 water organisms 10-1mg/1/96 hours				
	Aquatic toxicity rate TLm96 : 10-1 ppm				
	5.3 mg/l poisonous for trout after 8 days, from 1 mg/l				
	carcinogen for water organisms.				

# **13. DISPOSAL CONSIDERATIONS**



13.1 Product :

ACE Royal Tech Inc. T.031-383-0969 F.02-6230-9269 http://www.aceroyalco.kr e-mail; marketing@aceroyalco.kr

13.2 Soiled package :

Compact material is recycled(e.g. controlled thermal decomposition) or disposed according to RCRA Hazardous Waste Regulations or state regulations (in Unitd States). Special package for GaAs wafers can be reused after special cleaning, other package contaminated by As to be disposed of in controlled dumps.

14. TRANSPORT INFORMATION			
14.1 Transport classification :	UN-number	Not assigned	
	(ADR/RID; GGVS/GGVI	E; AND/ADNR; IMDG/GGVSee;	
	ICAO-TI ; IATA-DGR)	Not applicable	
14.2 Transport information :	rmation : There are no special regulations since GaAsP epita		
	not hazardous under normal transport conditions (fir impact of acids excluded). This is also true, if GaAsP ep		
	wafer is released from pacl	kage in an accident.	

### **15. REGULATORY INFORMATION**

Follow all regulations in your country.

### **16. OTHER INFORMATION**

#### 16.1 References :

- ACGIH TLVs and BEIs Threshold Limit Values for Chemical Substances and Physical Agents(1998)
- 2) SAX's Dangerous Properties of Industrial Materials (1995)
- 3) Roschina T.A. : Gig Tr Prof Zabol, 10 ; 30-33, (1966)
- 4) Fadeev A.I. : Gig Tr Prof Zabol, 24(3), 45, (1980)
- 5) MSDS Freiberger Compound Materials GmbH (1997)
- 6) NTP Chemical Repository Gallium Arsenide (Radian Corporation 1990)
- 7) Ohyama S. : Applied Organometallic Chemistry, 2, 333, (1988)
- 8) MSDS Hewlett-Packard Opto Electronics Division (1996)

Aforementioned data are based on our present knowledge and experience. The data sheet describes our product with regard to safety requirements but does not guarantee properties.

The buyer of our products is responsible for observing valid laws and regulations.